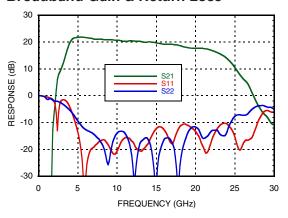
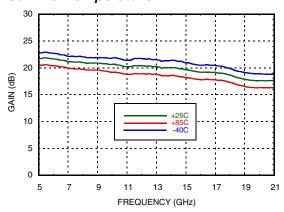


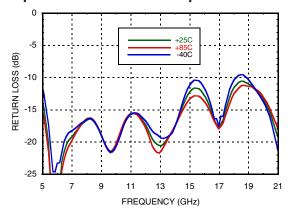
Broadband Gain & Return Loss



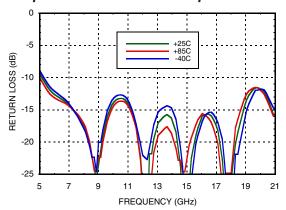
Gain vs. Temperature



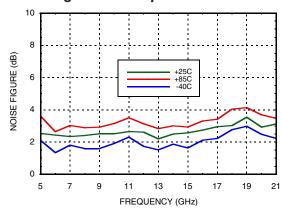
Input Return Loss vs. Temperature



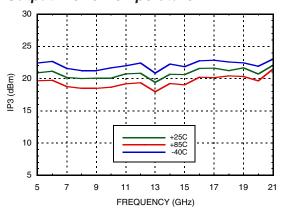
Output Return Loss vs. Temperature



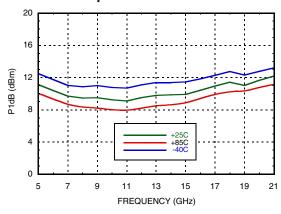
Noise Figure vs. Temperature



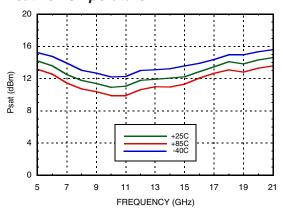
Output IP3 vs. Temperature



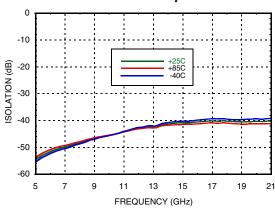
P1dB vs. Temperature



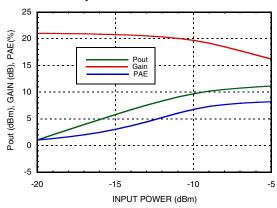
Psat vs. Temperature



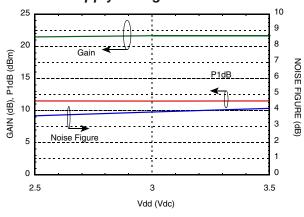
Reverse Isolation vs. Temperature



Power Compression @ 12 GHz



Gain, Noise Figure & Power vs. Supply Voltage @ 12 GHz





GaAs SMT PHEMT LOW NOISE

AMPLIFIER, 6 - 20 GHz

Absolute Maximum Ratings

Drain Bias Voltage (Vdd1, Vdd2, Vdd3)	+3.5 Vdc	
RF Input Power (RFIN)(Vdd = +3.0 Vdc)	10 dBm	
Channel Temperature	175 °C	
Continuous Pdiss (T= 85 °C) (derate 8.5 mW/°C above 85 °C)	0.753 W	
Thermal Resistance (channel to ground paddle)	119.5 °C/W	
Storage Temperature	-65 to +150 °C	
Operating Temperature	-40 to +85 °C	
ESD Sensitivity (HBM)	Class 1A	

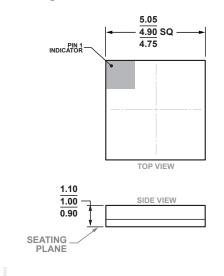
Typical Supply Current vs. Vdd

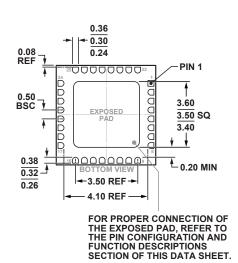
(mA)
1
3
6



ELECTROSTATIC SENSITIVE DEVICE **OBSERVE HANDLING PRECAUTIONS**

Outline Drawing





32-Terminal Ceramic Leadless Chip Carrier [LCC] (E-32-1) Dimensions shown in millimeters.

ORDERING GUIDE

Part Number	Package Material	Lead Finish	MSL Rating [1]	Package Marking [2]
HMC565LC5	Alumina, White	Gold over Nickle	MSL3	<u>H565</u> XXXX
HMC565LC5TR	Alumina, White	Gold over Nickle	MSL3	<u>H565</u> XXXX
HMC565LC5TR-R5	Alumina, White	Gold over Nickle	MSL3	<u>H565</u> XXXX

[1] Max peak reflow temperature of 260 °C

[2] 4-Digit lot number XXXX



Pin Descriptions

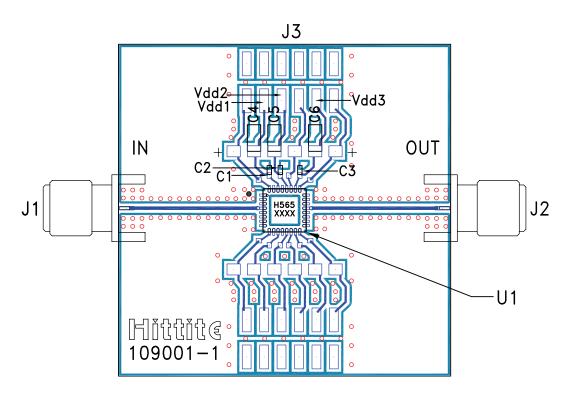
Pin Number	Function	Description Interface Schematic	
1, 2, 6 - 19, 23 - 25, 27, 29, 31, 32	N/C	This pin may be connected to RF/DC ground. Performance will not be affected.	
3, 5, 20, 22	GND	These pins and package bottom must be connected to RF/DC ground.	GND =
4	RFIN	This pin is AC coupled and matched to 50 Ohms.	RFIN ○──
21	RFOUT	This pin is AC coupled and matched to 50 Ohms.	— —○ RFOUT
30, 28, 26	Vdd1, 2, 3	Power Supply Voltage for the amplifier. External bypass capacitors of 100 pF and 2.2 μF are required.	Vdd1,2,3

Application Circuit

Component V	/alue				
	00 pF	Vdd1	Vdd2	Vdd3	
	2.2 µF	P	9	9	
04, 03, 00 2	Σ μι				
		±C1 C4±	\pm C2 C5 \pm	±C3 C6±	
		± ±	= =	= =	
		30	28	26	
	RFIN	4		21	— ⟨RFOUT



Evaluation PCB



List of Materials for Evaluation PCB 110431 [1]

Item	Description
J1 - J2	PCB Mount K Connector
J3	2 mm DC Header
C1 - C3	100 pF Capacitor, 0402 Pkg.
C4 - C6	2.2 µF Capacitor, Tantalum
U1	HMC565LC5 Amplifier
PCB [2]	109001 Evaluation PCB

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Analog Devices upon request.